



# SOT707-1

plastic thermal enhanced ball grid array package; 584 balls;  
body 37.5 x 37.5 x 1.42 mm; heatsink

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	HBGA584
<b>Package type industry code</b>	HBGA584
<b>Package style descriptive code</b>	HBGA (thermal enhanced ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	22-11-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	37.3	-	37.5	37.7	mm
E	package width	37.3	-	37.5	37.7	mm
A	seated height	[tbd]	-	2.15	2.15	mm
A <sub>2</sub>	package height	1.35	-	1.42	1.5	mm
n <sub>2</sub>	actual quantity of termination	-	-	584	-	

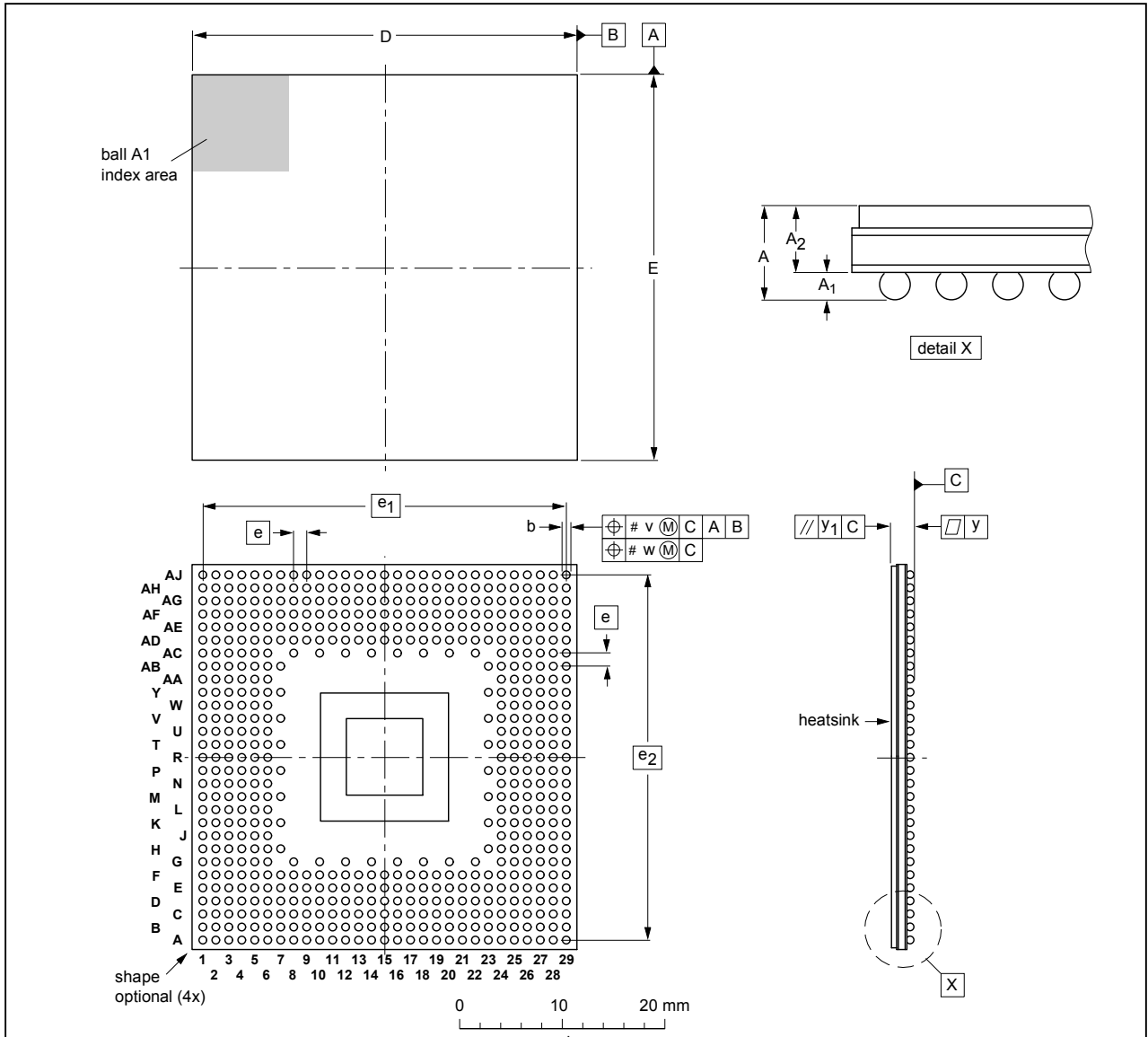


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## 2. Package outline

HBGA584: plastic thermal enhanced ball grid array package; 584 balls;  
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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	b	D	E	e	e <sub>1</sub>	e <sub>2</sub>	v	w	y	y <sub>1</sub>
mm	2.15	0.65 0.45	1.50 1.35	0.7 0.6	37.7 37.3	37.7 37.3	1.27	35.56	35.56	0.3	0.1	0.15	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT707-1						02-11-22

Fig. 1. Package outline HBGA584 (SOT707-1)

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### 3. Legal information

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